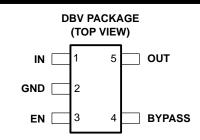
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- 150-mA Low Noise, Low-Dropout Regulator
- Output Voltage: 2.5 V, 2.7 V, 2.8 V, 3.0 V, 3.3 V
- Output Noise Typically 50 μV
- Quiescent Current Typically 85 μA
- Dropout Voltage, Typically 300 mV at 150 mA
- Thermal Protection
- Over Current Limitation
- Less Than 2-μA Quiescent Current in Shutdown Mode
- –40°C to 125°C Operating Junction Temperature Range
- 5-Pin SOT-23 (DBV) Package



### description

The TPS764xx family of low-dropout (LDO) voltage regulators offers the benefits of a low noise, low-dropout voltage, low-power operation, and miniaturized package. Additionally, they feature low quiescent current when compared to conventional LDO regulators. Offered in 5-terminal small outline integrated-circuit SOT-23 package, the TPS764xx series devices are ideal for low-noise applications, cost-sensitive designs and applications where board space is at a premium.

A combination of new circuit design and process innovation has enabled the usual pnp pass transistor to be replaced by a PMOS pass element. Because the PMOS pass element behaves as a low-value resistor, the dropout voltage is very low—typically 300 mV at 150 mA of load current (TPS76433)—and is directly proportional to the load current. Since the PMOS pass element is a voltage-driven device, the quiescent current is very low (140 µA maximum) and is stable over the entire range of output load current (0 mA to 150 mA). Intended for use in portable systems such as laptops and cellular phones, the low-dropout voltage feature and low-power operation result in a significant increase in system battery operating life.

The TPS764xx also features a logic-enabled sleep mode to shut down the regulator, reducing quiescent current to 1  $\mu$ A maximum at T<sub>.1</sub> = 25°C. The TPS764xx is offered in 2.5-V, 2.7-V, 2.8-V, 3.0-V, and 3.3-V fixed-voltages.

### **AVAILABLE OPTIONS**

TJ	VOLTAGE	PACKAGE	PART N	UMBER	SYMBOL
	2.5 V		TPS76425DBVT†	TPS76425DBVR‡	PBJI
	2.7 V		TPS76427DBVT†	TPS76427DBVR‡	PBKI
–40°C to 125°C	2.8 V	SOT-23 (DBV)	TPS76428DBVT <sup>†</sup>	TPS76428DBVR <sup>‡</sup>	PCEI
	3.0 V	(557)	TPS76430DBVT <sup>†</sup>	TPS76430DBVR <sup>‡</sup>	PBLI
	3.3 V		TPS76433DBVT <sup>†</sup>	TPS76433DBVR‡	PBMI

<sup>†</sup> The DBVT passive indicates tape and reel of 250 parts.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

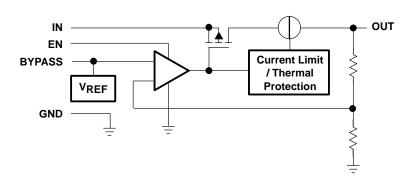


<sup>&</sup>lt;sup>‡</sup> The DBVR passive indicates tape and reel of 3000 parts.

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### functional block diagram

### TPS76425/27/28/30/33



### **Terminal Functions**

TERMINAL NAME	1/0	DESCRIPTION
GND		Ground
EN	I	Enable input
BYPASS		Output bypass capacitor
IN	_	Input supply voltage
OUT	0	Regulated output voltage

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Input voltage range (see Note 1)	0.3 V to 10 V
Voltage range at EN	0.3 V to V <sub>I</sub> + 0.3 V
Voltage on OUT,	
Peak output current	Internally limited
ESD rating, HBM	2 kV
Continuous total power dissipation	See dissipation rating tables
Operating virtual junction temperature range, T <sub>J</sub>	–40°C to 150°C
Storage temperature range, T <sub>stg</sub>	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network ground terminal.

### **DISSIPATION RATING TABLE**

BOARD	PACKAGE	$R_{ heta}$ JC	$R_{ heta JA}$	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	$T_{\mbox{\scriptsize A}} \leq 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING
Low K‡	DBV	65.8 °C/W	259 °C/W	3.9 mW/°C	386 mW	212 mW	154 mW
High K§	DBV	65.8 °C/W	180 °C/W	5.6 mW/°C	555 mW	305 mW	222 mW

<sup>†</sup> The JEDEC Low K (1s) board design used to derive this data was a 3 inch x 3 inch, two layer board with 2 ounce copper traces on top of the board. § The JEDEC High K (2s2p) board design used to derive this data was a 3 inch x 3 inch, multilayer board with 1 ounce internal power and ground



planes and 2 ounce copper traces on top and bottom of the board.

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### recommended operating conditions

	MIN	NOM	MAX	UNIT
Input voltage, V <sub>I</sub> †	2.7		10	V
Continuous output current, IO	0		150	mA
Operating junction temperature, T <sub>J</sub>	-40		125	°C

<sup>†</sup> To calculate the minimum input voltage for your maximum output current, use the following equation:  $V_{I(min)} = V_{O(max)} + V_{DO(max load)}$ 

## electrical characteristics over recommended operating free-air temperature range, V<sub>I</sub> = V<sub>O(typ)</sub> + 1 V, I<sub>O</sub>= 1 mA, EN = IN, C<sub>o</sub> = 4.7 $\mu\text{F}$ (unless otherwise noted)

	PARAMETER		TEST CON	NDITIONS	MIN	TYP	MAX	UNIT		
			I <sub>O</sub> = 1 mA to 100 mA,	T <sub>J</sub> = 25°C	2.45	2.5	2.55			
		TPS76425	I <sub>O</sub> = 1 mA to 100 mA		2.425	2.5	2.575	V		
		117576425	$I_O = 1 \text{ mA to } 150 \text{ mA}, \qquad T_J = 25^{\circ}\text{C}$ 2.438		2.438	2.5	2.562	V		
			I <sub>O</sub> = 1 mA to 150 mA		2.407	2.5	2.593			
			$I_O = 1 \text{ mA to } 100 \text{ mA},$	T <sub>J</sub> = 25°C	2.646	2.7	2.754			
		TPS76427	I <sub>O</sub> = 1 mA to 100 mA		2.619	2.7	2.781	V		
		175/042/	$I_O = 1 \text{ mA to } 150 \text{ mA},$	T <sub>J</sub> = 25°C	2.632	2.7	2.768	V		
			I <sub>O</sub> = 1 mA to 150 mA		2.598	2.7	2.8013			
			$I_O = 1 \text{ mA to } 100 \text{ mA}$	T <sub>J</sub> = 25°C	2.744	2.8	2.856			
٧o	Output voltage	TPS76428	$I_O = 1 \text{ mA to } 150 \text{ mA},$	_	2.73	2.8	2.870	V		
*0	Output voltage	17370420	$I_O = 1 \text{ mA to } 150 \text{ mA},$	T <sub>J</sub> = 25°C	2.716	2.8	2.884	V		
			I <sub>O</sub> = 1 mA to 150 mA		2.695	2.8	2.905			
		TPS76430	$I_O = 1 \text{ mA to } 100 \text{ mA},$	T <sub>J</sub> = 25°C	2.94	3.0	3.06			
			I <sub>O</sub> = 1 mA to 100 mA		2.925	3.0	3.075	V		
			$I_O = 1 \text{ mA to } 150 \text{ mA},$	T <sub>J</sub> = 25°C	2.91	3.0	3.090	v		
			$I_O = 1 \text{ mA to } 150 \text{ mA}$		2.887	3.0	3.112			
			$I_O = 1 \text{ mA to } 100 \text{ mA},$	T <sub>J</sub> = 25°C	3.234	3.3	3.366			
			$I_O = 1 \text{ mA to } 100 \text{ mA}$	= 1 mA to 100 mA 3.201		3.3	3.399	\ <sub>\</sub>		
		11570433	$I_O = 1 \text{ mA to } 150 \text{ mA},$	T <sub>J</sub> = 25°C	3.218	3.3	3.382	V		
			$I_O = 1 \text{ mA to } 150 \text{ mA}$		3.177	3.3	3.423			
I <sub>(Q)</sub>	Quiescent current	nn+\	I <sub>O</sub> = 0 to 150 mA, See Note 2	T <sub>J</sub> = 25°C,		85	100			
(-)	(GND terminal curre	ent)	I <sub>O</sub> = 0 to 150 mA,	See Note 2			140	μΑ		
	Ctondby ourrent		EN < 0.5 V,	T <sub>J</sub> = 25°C		0.5	1			
	Standby current		EN < 0.5 V				2			
V <sub>n</sub>	Output noise voltage		BW = 300 Hz to 50 kHz, $T_J = 25^{\circ}C$ ,	C <sub>O</sub> = 10 μF, See Note 2		50		μV		
	Bypass voltage		T <sub>J</sub> = 25°C			1.192		V		
PSRR	Ripple rejection		$f = 1 \text{ kHz}, \ C_0 = 10 \ \mu\text{F},$	T <sub>J</sub> = 25°C, See Note 2		60		dB		
	Current limit		T <sub>J</sub> = 25°C	See Note 3		0.8	1.5	Α		

NOTES: 2. Minimum IN operating voltage is 2.7 V or  $V_{O(typ)}$  + 1 V, whichever is greater. 3. Test condition includes, output voltage  $V_{O}$ =0 V and pulse duration = 10 mS.



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## electrical characteristics over recommended operating free-air temperature range, $V_I = V_{O(typ)} + 1$ V, $I_{O} = 1$ mA, EN = IN, $C_o = 4.7~\mu F$ (unless otherwise noted) (continued)

	PARAMETER		TEST CO	ONDITIONS	MIN	TYP	MAX	UNIT	
	Output voltage line regulation (/	7/O//O)	$V_{O} + 1 V < V_{I} \le 10 V$ ,	V <sub>I</sub> ≥ 3.5 V, T <sub>J</sub> = 25°C		0.04	0.07	%/V	
	(see Note 4)		$V_{O} + 1 V < V_{I} \le 10 V$ ,	V <sub>I</sub> ≥ 3.5 V			0.1	76/ V	
VIH	EN high level input		See Note 2			1.4	2	V	
$V_{IL}$	EN low level input		See Note 2		0.5	1.2		V	
١.	EN input current		EN = 0 V			-0.01	-0.5	μΑ	
li	Liv input current		EN = IN			-0.01	-0.5	μΑ	
			$I_O = 0 \text{ mA},$	T <sub>J</sub> = 25°C		0.2			
			$I_O = 1 \text{ mA},$	T <sub>J</sub> = 25°C		3			
			$I_{O} = 50 \text{ mA},$	T <sub>J</sub> = 25°C		120	150		
			I <sub>O</sub> = 50 mA				200		
		TPS76425	$I_{O} = 75 \text{ mA},$	T <sub>J</sub> = 25°C		180	225	mV	
			I <sub>O</sub> = 75 mA				300		
			I <sub>O</sub> = 100 mA,	T <sub>J</sub> = 25°C		240	300		
			I <sub>O</sub> = 100 mA				400	400 450	
			I <sub>O</sub> = 150 mA,	T <sub>J</sub> = 25°C		360	450		
\/==	Dropout voltage (see Note 5)		I <sub>O</sub> = 150 mA				600		
VDO	Diopout voitage (see Note 5)		$I_O = 0 \text{ mA},$	T <sub>J</sub> = 25°C		0.2			
			$I_O = 1 \text{ mA},$	T <sub>J</sub> = 25°C		3			
			$I_{O} = 50 \text{ mA},$	T <sub>J</sub> = 25°C		100	125		
			I <sub>O</sub> = 50 mA				166		
		TPS76433	I <sub>O</sub> = 75 mA,	T <sub>J</sub> = 25°C		150	188	mV	
		11570433	I <sub>O</sub> = 75 mA				250	IIIV	
			I <sub>O</sub> = 100 mA,	T <sub>J</sub> = 25°C		200	250		
			I <sub>O</sub> = 100 mA				333		
			I <sub>O</sub> = 150 mA,	T <sub>J</sub> = 25°C		300	375		
			I <sub>O</sub> = 150 mA				500		

NOTES: 2. Minimum IN operating voltage is 2.7 V or  $V_{O(typ)}$  + 1 V, whichever is greater. 4. If  $V_{O}$  < 2.5 V and  $V_{Imax}$  = 10 V,  $V_{Imin}$  = 3.5 V:

Line Reg. (mV) = 
$$(\%/V) \times \frac{V_O(V_{lmax} - 3.5 \text{ V})}{100} \times 1000$$

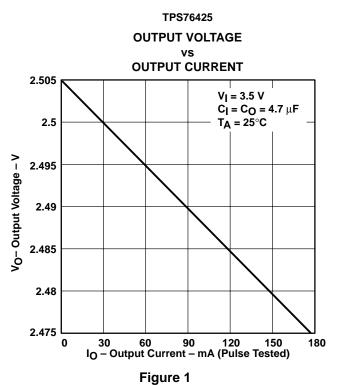
If  $V_O > 2.5 \text{ V}$  and  $V_{Imax} = 10 \text{ V}$ ,  $V_{Imin} = V_O + 1 \text{ V}$ :

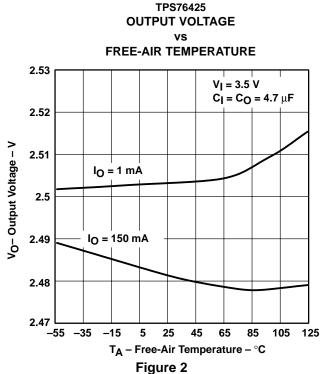
Line Reg. (mV) = 
$$(\%/V) \times \frac{V_O(V_{Imax} - (V_O + 1))}{100} \times 1000$$

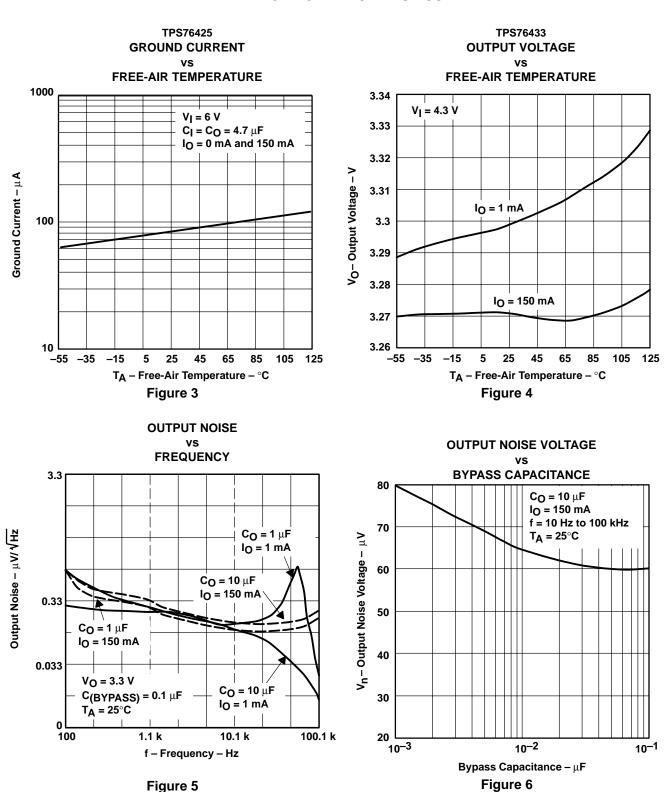
5. Dropout voltage is defined as the differential voltage between VO and VI when VO drops 100 mV below the value measured with  $V_{I} = V_{O} + 1.0 V.$ 

### **Table of Graphs**

			FIGURE
\/-	Quitaut valta aa	vs Output current	1
VO	Output voltage	vs Free-air temperature	2, 3, 4
$V_n$	Output noise	vs Frequency	5
V	Output poice valtage	vs Bypass capacitance	6
V <sub>n</sub>	Output noise voltage	vs Load current	7
Z <sub>0</sub>	Output impedance	vs Frequency	8
$V_{DO}$	Dropout voltage	vs Free-air temperature	9
	Ripple rejection	vs Frequency	10
	Line transient response		11, 13
	Load transient response		12, 14
	Companyation parios registance (CSP)	vs Output current	15, 17
	Compensation series resistance (CSR)	vs Added ceramic capacitance	16, 18









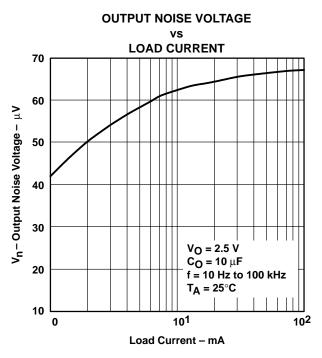
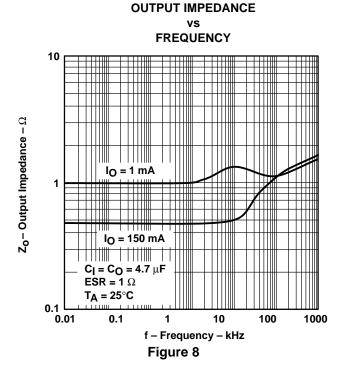
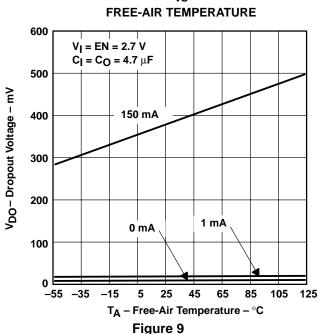


Figure 7



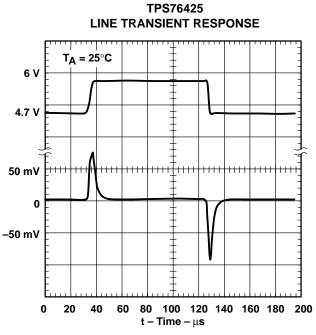
TPS76425 DROPOUT VOLTAGE VS REE-AIR TEMPERATURE



**FREQUENCY** 100  $V_0 = 2.5 \text{ V}$ 90  $C(BYPASS) = 0.01 \mu F$  $C_L = 10 \,\mu\text{F}$ 80 Ripple Rejection - dB 70  $I_0 = 1 \text{ mA}$ 60 50 I<sub>O</sub> = 150 mA 40 30 20 10 0 1 M 10 100 1 k 10 k 100 k 10 M f - Frequency - Hz Figure 10

**TPS76425** 

RIPPLE REJECTION





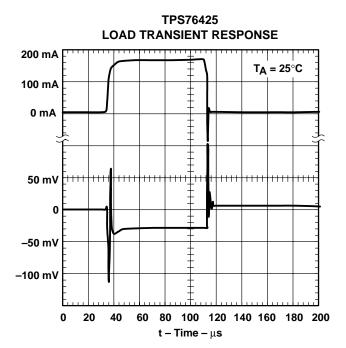


Figure 12

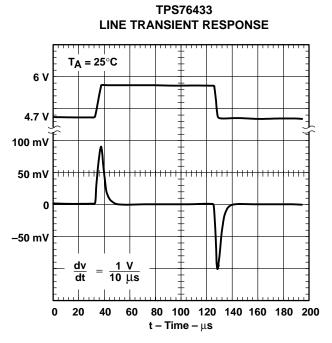
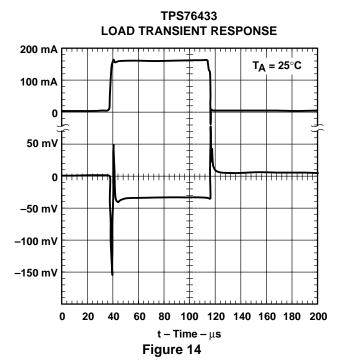
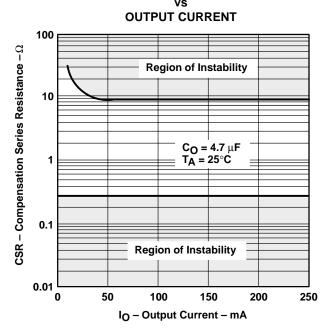


Figure 13



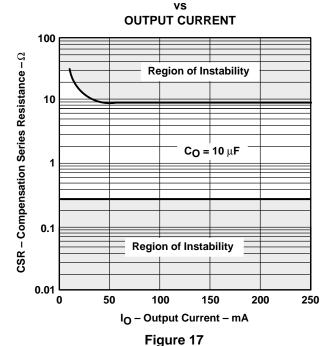
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## TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE (CSR) $^\dagger$

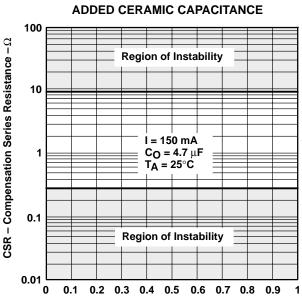


TYPICAL REGIONS OF STABILITY
COMPENSATION SERIES RESISTANCE (CSR)<sup>†</sup>

Figure 15



# TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE (CSR)† vs



Added Ceramic Capacitance –  $\mu$ F

Figure 16

## TYPICAL REGIONS OF STABILITY COMPENSATION SERIES RESISTANCE (CSR) $^{\dagger}$

### ADDED CERAMIC CAPACITANCE

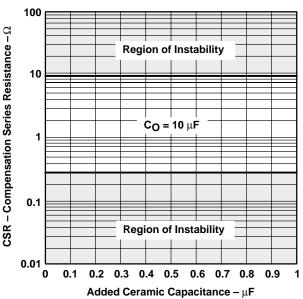


Figure 18

<sup>†</sup> CSR refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to C<sub>O</sub>.



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### APPLICATION INFORMATION

The TPS764xx family of low-noise and low-dropout (LDO) regulators are optimized for use in battery-operated equipment. They feature extremely low noise (50  $\mu$ V), low dropout voltages, low quiescent current (140  $\mu$ A), and an enable input to reduce supply current to less than 2  $\mu$ A when the regulator is turned off.

### device operation

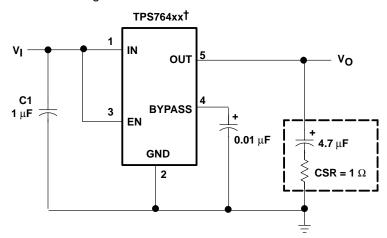
The TPS764xx uses a PMOS pass element to dramatically reduce both dropout voltage and supply current over more conventional PNP-pass-element LDO designs. The PMOS pass element is a voltage-controlled device which, unlike a PNP transistor, does not require increased drive current as output current increases. Supply current in the TPS764xx is essentially constant from no-load to maximum load.

Current limiting and thermal protection prevent damage by excessive output current and/or power dissipation. The device switches into a constant-current mode at approximately 1 A; further load reduces the output voltage instead of increasing the output current. The thermal protection shuts the regulator off if the junction temperature rises above 165°C. Recovery is automatic when the junction temperature drops approximately 25°C below the high temperature trip point. The PMOS pass element includes a back diode that safely conducts reverse current when the input voltage level drops below the output voltage level.

An internal resistor, in conjunction with external 0.01- $\mu$ F bypass capacitor, creates a low-pass filter to further reduce the noise. The TPS764xx exhibits only 50  $\mu$ V of output voltage noise using 0.01  $\mu$ F bypass and 4.7- $\mu$ F output capacitors.

A logic low on the enable input, EN, shuts off the output and reduces the supply current to less than 2  $\mu$ A. EN should be tied high in applications where the shutdown feature is not used.

A typical application circuit is shown in Figure 19.



† TPS76425, TPS76427 TPS76430, TPS76433.

Figure 19. Typical Application Circuit



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### **APPLICATION INFORMATION**

### external capacitor requirements

Although not required, a  $0.047-\mu F$  or larger ceramic bypass input capacitor, connected between IN and GND and located close to the TPS764xx, is recommended to improve transient response and noise rejection. A higher-value electrolytic input capacitor may be necessary if large, fast-rise-time load transients are anticipated and the device is located several inches from the power source.

Like all low dropout regulators, the TPS764xx requires an output capacitor connected between OUT and GND to stabilize the internal loop control. The minimum recommended capacitance value is 4.7  $\mu$ F and the ESR (equivalent series resistance) must be between 0.2  $\Omega$  and 10  $\Omega$ . Capacitor values 4.7  $\mu$ F or larger are acceptable, provided the ESR is less than 10  $\Omega$ . Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Most of the commercially available 4.7  $\mu$ F surface-mount solid tantalum capacitors, including devices from Sprague, Kemet, and Nichico, meet the ESR requirements previously stated. Multilayer ceramic capacitors should have minimum values of 1  $\mu$ F over the full operating temperature range of the equipment.

### **CAPACITOR SELECTION**

PART NO.	MFR.	VALUE	MAX ESR <sup>†</sup>	SIZE $(H \times L \times W)^{\dagger}$
T494B475K016AS	KEMET	4.7 μF	1.5 Ω	$1.9\times3.5\times2.8$
195D106x0016x2T	SPRAGUE	10 μF	1.5 Ω	$1.3\times7.0\times2.7$
695D106x003562T	SPRAGUE	10 μF	1.3 Ω	$2.5\times7.6\times2.5$
TPSC475K035R0600	AVX	4.7 μF	0.6 Ω	$2.6 \times 6.0 \times 3.2$

<sup>†</sup> Size is in mm. ESR is maximum resistance in ohms at 100 kHz and T<sub>A</sub> = 25°C. Listings are sorted by height.

### APPLICATION INFORMATION

### power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of  $125^{\circ}$ C; the maximum junction temperature allowable without damaging the device is  $150^{\circ}$ C. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation,  $P_{D(max)}$ , and the actual dissipation,  $P_D$ , which must be less than or equal to  $P_{D(max)}$ .

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_J max - T_A}{R_{\theta JA}}$$

Where:

T<sub>J</sub>max is the maximum allowable junction temperature

R<sub>0.JA</sub> is the thermal resistance junction-to-ambient for the package, see the dissipation rating table.

T<sub>A</sub> is the ambient temperature.

The regulator dissipation is calculated using:

$$P_D = (V_I - V_O) \times I_O$$

Power dissipation resulting from quiescent current is negligible.

### regulator protection

The TPS764xx pass element has a built-in back diode that safely conducts reverse current when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. If extended reverse voltage is anticipated, external limiting might be appropriate.

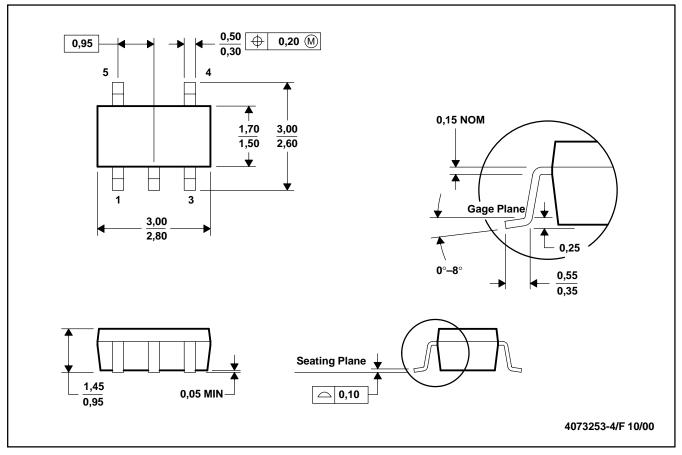
The TPS764xx also features internal current limiting and thermal protection. During normal operation, the TPS764xx limits output current to approximately 800 mA. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 165°C, thermal-protection circuitry shuts it down. Once the device has cooled down to below 140°C, regulator operation resumes.

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### **MECHANICAL DATA**

### DBV (R-PDSO-G5)

### PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-178







### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TPS76425DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76425DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76425DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76425DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76427DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76427DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76427DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76427DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76428DBV	OBSOLETE	SOT-23	DBV	5		TBD	Call TI	Call TI
TPS76428DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76428DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76428DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76428DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76430DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76430DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76430DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76430DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76433DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76433DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76433DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS76433DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check



### PACKAGE OPTION ADDENDUM

5-Feb-2007

http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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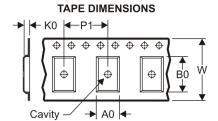




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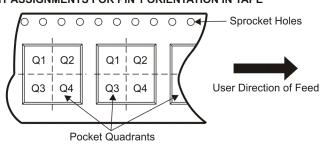
### TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
Г	W	Overall width of the carrier tape
Г	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS76425DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76425DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76427DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76427DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76428DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76428DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76430DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76430DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76433DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS76433DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3





\*All dimensions are nominal

All difficultions are norminal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS76425DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76425DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS76427DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76427DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS76428DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76428DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS76430DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76430DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS76433DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS76433DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0

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